

TSG-RAN Meeting #8
Düsseldorf, Germany, 21 - 23 June 2000

RP-000292

Agenda Item: 6
Source: CWTS
To: TSG-RAN #8
Title: Work Item Description "Low Chip Rate TDD Physical Layer"
Document for: Approval

Work Item Description

Title

Low chip rate TDD physical layer

1 3GPP Work Area

X	Radio Access
	Core Network
	Services

2 Linked work items

Low Chip Rate TDD UE capabilities
Low chip rate TDD Layer 2 and Layer 3 protocol aspects
Low chip rate TDD UTRAN architecture aspects
Smart Antenna
RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing

3 Justification

The integration of TDD low chip rate option in Release 2000 is discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. This paper is to describe one of the low chip rate TDD building blocks – Physical layer.

4 Objective

The technical objective of this work item is clarify the building block of physical layer. And this work will affect the specifications for working group on physical layer.

- For physical layer, it includes the following work tasks:
 - Physical Channels and Mapping of Transport Channels onto Physical Channels
 - Multiplexing and Channel Coding
 - Modulation and spreading
 - Physical layer procedures
 - Physical Layer Measurements

Task	Planned Start	Planned Finish
Create possible new TR on low chip rate TDD	01/2000	05/2000
RAN#8 decide whether new specification required	06/2000	06/2000
Drafting new specifications and CRs	06/2000	09/2000
Possible remaining corrections and clarifications	09/2000	12/2000

5 Service Aspects

None

6 MMI-Aspects

None

7 Charging Aspects

None

8 Security Aspects

None

9 Impacts

Affects :	USIM	ME	AN	CN	Others
Yes		X	X		
No	X			X	X
Don't know					

10 Expected Output and Time scale (to be updated at each plenary)

New specifications						
Spec No.	Title	Prime resp. WG	2ndary resp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments
Affected existing specifications						
Spec No.	CR	Subject			Approved at plenary#	Comments
25.201		Physical layer – General description			RAN#9	
25.221		Physical channels and mapping of transport channels onto physical channels (TDD)			RAN#9	
25.222		Multiplexing and channel coding (TDD)			RAN#9	
25.223		Spreading and modulation (TDD)			RAN#9	
25.224		TDD; physical layer procedures			RAN#9	
25.225		Physical layer; measurements			RAN#9	
25.302		Services Provided by the physical layer			RAN#9	

11 Work item rapporteurs

Mr. Guiliang Yang (CATT/CWTS)

12 Work item leadership

RAN WG1

13 Supporting Companies

14 Classification of the WI (if known)

	Feature (go to 14a)
X	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)

The building blocks should be discussed and approved via email discussion

14b The WI is a Building Block: parent Feature

(one Work Item identified as a feature)

Low chip rate TDD

14c The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)